

GL -VIACLEAN95



ADVANCED MELAMINE COATED HDF DRILL BACKER FOR CLEAN-HOLE PCB MANUFACTURING

WOOD FIBER HDF CONSTRUCTION WITH A LOW CONTENT MELAMINE RESIN FOR HIGH EFFICIENCY DRILL APPLICATIONS. DIMENSIONALLY STABLE AND EXCELLENT SURFACE FINISH LEAD TO CLEANER HOLES, MORE-EFFICIENT HIGH SPEED & ADVANCED MACHINING.

.095" +/- .005" THICKNESS: 37" X 49", 43" X 49", OR PRECUT AND TOOLED PANELS

SPECIAL FEATURES:

- MINIMIZE BURRING – APPROVED SURFACE HARDNESS TO MINIMIZE COPPER BURRS ON DRILL EXIT.
- MINIMIZE RESIN SMEAR - THE CONSISTENT HIGH DENSITY CORE PROVIDES EXCELLENT DRILL CHIPPING AND CLEANING
- PROMOTES LONGER DRILL LIFE - HDF CHIP CLEANS EASILY FROM THE DRILL FLUTE TO AVOID BUILDUP AND TOOL BREAKAGE
- IMPROVED HOLE WALL QUALITY – CLEANER HOLES, NO CONTAMINANTS, MORE CONSISTENT RESULTS

Technical Data

Thickness and Tolerance	2.45mm/ 0.095"	Surface Hardness	75 +/-5
Thickness Swelling	<35%	Surface Finish	Matte
Moisture	<7%	Density	90 0+/- 30Kg/m3
Warpage	<0.6% on diagonal	Formaldehyde Release	<0.3ppm
Internal Bond Strength	>1.8MPa	MOR	>Mpa

